



Pb Free Product



30V Half Bridge Dual N-Channel Enhancement Mode Power MOSFET

Description

The NCEB301G is designed to provide a high efficiency synchronous buck power stage with optimal layout and board space utilization. It includes two specialized MOSFETs in a dual Power DFN5x6 package. The Q1 "High Side" MOSFET is desgined to minimze switching losses. The Q2"Low Side" MOSFET uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge.

General Features

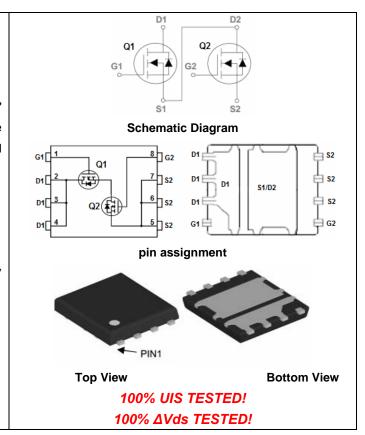
Q1 "High Side" MOSFET Q2 "Low Side" MOSFET

$$\begin{split} \bullet \ V_{DS} = & 30 \text{V}, I_D = & 20 \text{A} \\ R_{DS(ON)} < & 8.5 \text{m} \Omega \ @ \ V_{GS} = & 10 \text{V} \\ R_{DS(ON)} < & 14 \text{m} \Omega \ @ \ V_{GS} = & 4.5 \text{V} \\ \end{split}$$

- Excellent gate charge x R_{DS(on)} product(FOM)
- Very low on-resistance R_{DS(on)}
- 150 °C operating temperature
- Pb-free lead plating
- 100% UIS tested

Application

• Compact DC/DC converter applications



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCEB301G	NCEB301G	DFN5X6-8L	-	-	-

Absolute Maximum Ratings (T_C=25 ℃unless otherwise noted)

	<u> </u>				
Paramet	Symbol	Q1	Q2	Unit	
Drain-Source Voltage	V_{DS}	30	30	V	
Gate-Source Voltage	V_{GS}	±20	±20	V	
Drain Current-Continuous (Note 2)	T _C =25°C	1	20	35	Α
	T _C =100°C	- I _D	14.1	24.7	Δ.
Drain Current -Pulsed (Note 1)		I _{DM}	80	120	А
Power Dissipation	T _C =25°C	P _D	20	40	W
Operating Junction and Storage Te	T_{J}, T_{STG}	-55 To 150	-55 To 150	$^{\circ}$	

Thermal Characteristic

Parameter	Symbol	Тур	Max	Unit
Thermal Resistance, Junction-to-Case (Note 2) (Q1)	R _{θJC}	6	6.3	°C/W
Thermal Resistance, Junction-to-Case (Note 2) (Q2)	R _{eJC}	2.9	3.1	°C/W



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Q1 Electrical Characteristics (T_C=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			•			
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	30	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)			•			
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_D=250\mu A$	1.0	1.5	2.2	V
Drain-Source On-State Resistance	В	V _{GS} =10V, I _D =10A	-	6.9	8.5	mΩ
Dialii-Source Oil-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =10A	-	10.8	14	mΩ
Forward Transconductance	g FS	V _{DS} =5V,I _D =10A	26	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{lss}	\/ 45\/\\ 0\/	-	1210	-	PF
Output Capacitance	Coss	V _{DS} =15V,V _{GS} =0V,	-	160	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz	-	105	-	PF
Switching Characteristics (Note 4)			•			
Turn-on Delay Time	t _{d(on)}		-	5	-	nS
Turn-on Rise Time	t _r	V_{DD} =15V, R_L =0.75 Ω	-	12	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10 V , R_{G} =3 Ω	-	19	-	nS
Turn-Off Fall Time	t _f		-	6	-	nS
Total Gate Charge	Qg	V 45VI 40A	-	17.5		nC
Gate-Source Charge	Q _{gs}	V _{DS} =15V,I _D =10A,	-	3		nC
Gate-Drain Charge	Q _{gd}	V _{GS} =10V	-	4.1		nC
Drain-Source Diode Characteristics			ı	1		
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =10A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	20	Α
Reverse Recovery Time	t _{rr}	TJ = 25°C, IF =10A	-	19	-	nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note3)}$	-	10	-	nC

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25 $^{\circ}\text{C}$,V $_{\text{DD}}$ =15V ,V $_{\text{G}}$ =10V ,L=0.5mH ,Rg=25 Ω





Q1Typical Electrical and Thermal Characteristics (Curves)

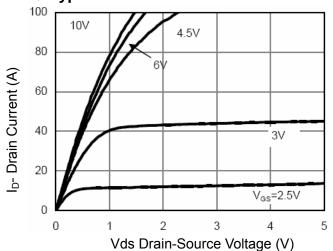


Figure 1 Output Characteristics

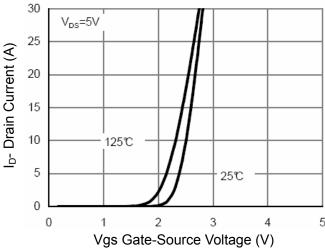


Figure 2 Transfer Characteristics

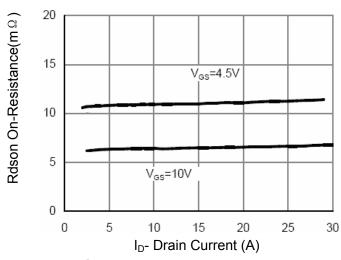


Figure 3 Rdson- Drain Current

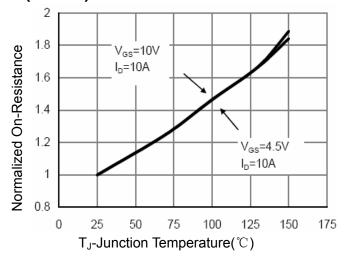


Figure 4 Rdson-Junction Temperature

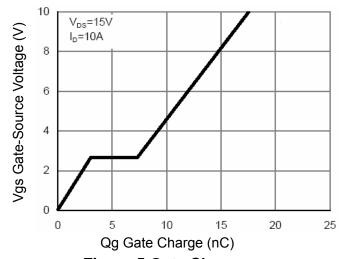


Figure 5 Gate Charge

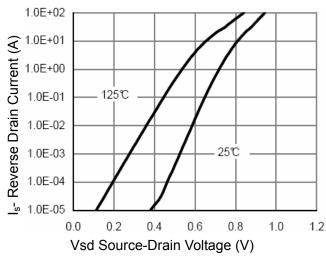
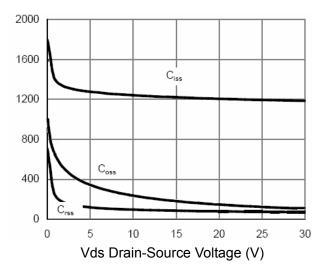


Figure 6 Source- Drain Diode Forward



C Capacitance (pF)



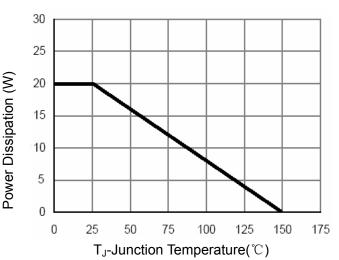
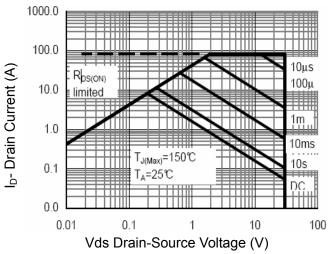


Figure 7 Capacitance vs Vds

Figure 9 Power De-rating



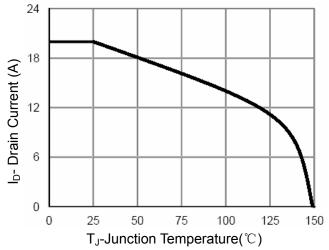
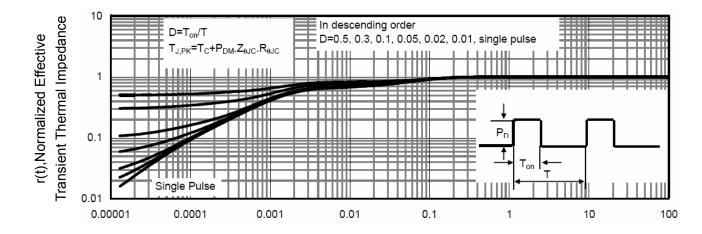


Figure 8 Safe Operation Area

Figure 10 I_D Current De-rating



Square Wave Pluse Duration(sec)

Figure 11 Normalized Maximum Transient Thermal Impedance



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Q2 Electrical Characteristics (TC=25 ℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit	
Off Characteristics							
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	30	33	-	V	
Zero Gate Voltage Drain Current	I _{DSS}	V_{DS} =30 V , V_{GS} =0 V	-	-	1	μA	
Gate-Body Leakage Current	I _{GSS}	V_{GS} =±20 V , V_{DS} =0 V	-	-	±100	nA	
On Characteristics (Note 3)							
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS} , I_D =250 μA	1	1.6	3	V	
Drain-Source On-State Resistance	В	V_{GS} =10V, I_D =12A	-	5.1	7.0	m0	
Dialii-Source Oil-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =10A	- 8.3 12.0		12.0	— mΩ	
Forward Transconductance	g FS	V _{DS} =10V,I _D =12A	30	-	-	S	
Dynamic Characteristics (Note4)							
Input Capacitance	C _{lss}	\/ -15\/\/ -0\/	-	2330	-	PF	
Output Capacitance	Coss	V_{DS} =15V, V_{GS} =0V, F=1.0MHz	-	460	-	PF	
Reverse Transfer Capacitance	C _{rss}	r-1.0ivinz	-	230	-	PF	
Switching Characteristics (Note 4)							
Turn-on Delay Time	t _{d(on)}		-	18	-	nS	
Turn-on Rise Time	tr	V_{DD} =15 V , I_D =12 A	-	10	-	nS	
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10 V , R_{GEN} =6 Ω	-	34	-	nS	
Turn-Off Fall Time	t _f		-	10	-	nS	
Total Gate Charge	Qg	V _{DS} =15V,I _D =12A,	-	45	-	nC	
Gate-Source Charge	Q_{gs}	V _{DS} -13V,I _D -12A, V _{GS} =10V	-	9.4	-	nC	
Gate-Drain Charge	Q_{gd}	V GS-10 V	-	7.7	-	nC	
Drain-Source Diode Characteristics							
Diode Forward Voltage (Note 3)	V_{SD}	V_{GS} =0 V , I_{S} =12 A	-	0.85	1.2	V	
Diode Forward Current (Note 2)	Is		-	-	35	Α	
Reverse Recovery Time	t _{rr}	TJ = 25°C, IF = 12A	-	-	47	nS	
Reverse Recovery Charge	Qrr	di/dt = 100A/µs(Note3)	-	-	25	nC	

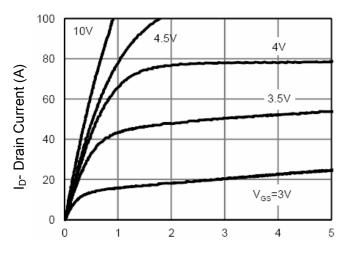
Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- **4.** Guaranteed by design, not subject to production
- **5.** EAS condition: Tj=25 $^{\circ}\text{C}$,VDD=15V,VG=10V,L=0.5mH,Rg=25 Ω



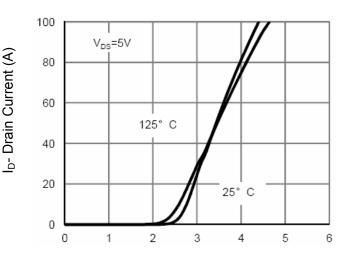


Q2 Typical Electrical and Thermal Characteristics (Curves)



Vds Drain-Source Voltage (V)

Figure 1 Output Characteristics



Vgs Gate-Source Voltage (V)
Figure 2 Transfer Characteristics

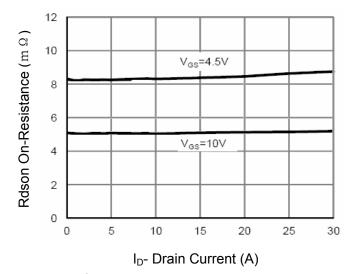


Figure 3 Rdson- Drain Current

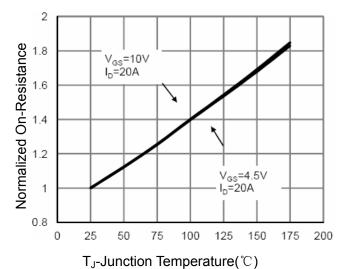


Figure 4 Rdson-Junction Temperature

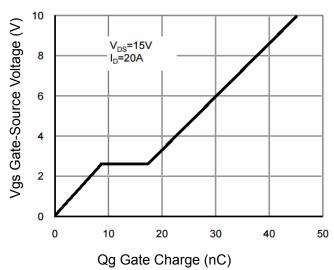


Figure 5 Gate Charge

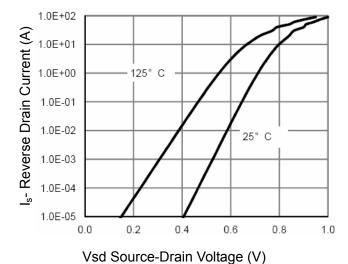


Figure 6 Source- Drain Diode Forward



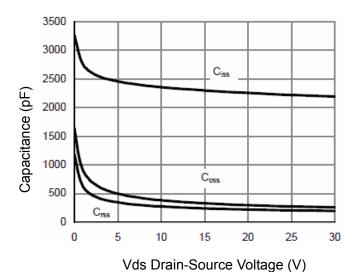
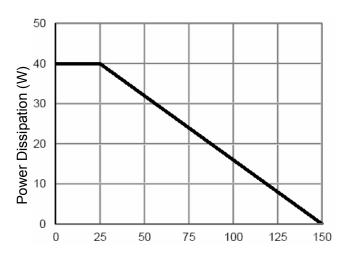


Figure 7 Capacitance vs Vds



 T_J -Junction Temperature($^{\circ}$ C) **Figure 9 Power De-rating**

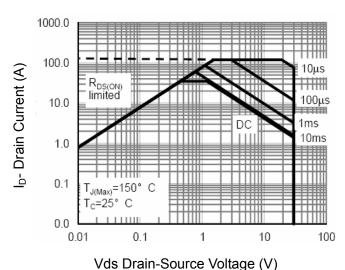


Figure 8 Safe Operation Area

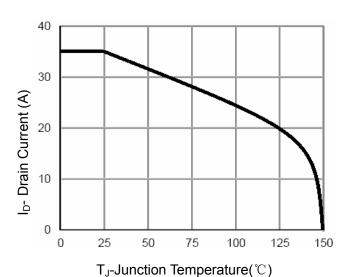


Figure 10 Current De-rating

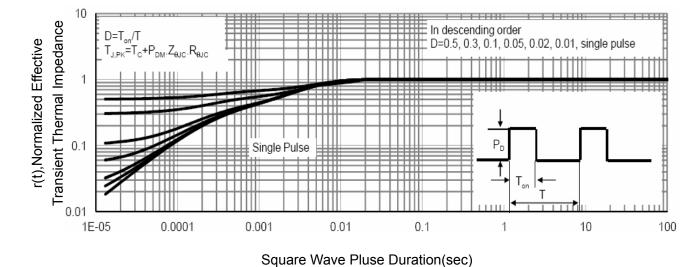
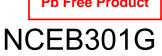
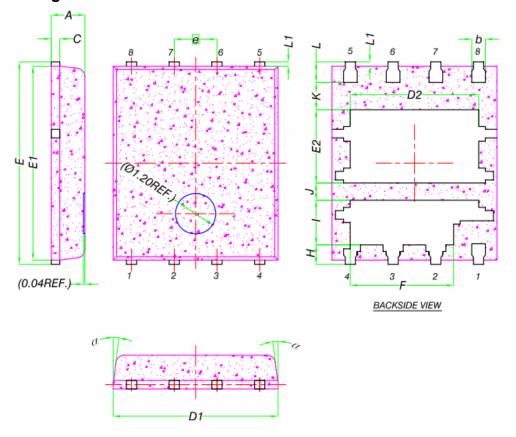


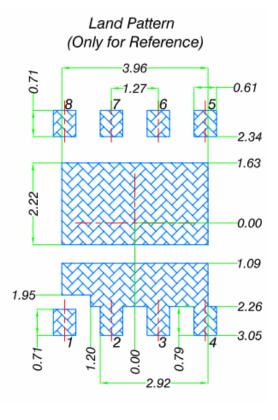
Figure 11 Normalized Maximum Transient Thermal Impedance



DFN5X6-8L Package Information



	MILLIMETERS					
DIM.	MIN. NOM.		MAX.			
Α	0.90	1.00	1.10			
b	0.33	0.41	0.51			
С	0.20	0.25	0.30			
D1	4.80	4.90	5.00			
D2	3.61	3.81	3.96			
Ε	5.90	6.00	6.10			
E1	5.70	5.75	5.80			
E2	2.02 2.17 2		2.32			
е	1.27 BSC					
F	2.87	3.07 3.2				
Н	0.48	0.58	0.68			
1	1.22	1.32	1.42			
J	0.40	0.50	0.60			
К	0.50	-	-			
L	0.51	0.61	0.71			
L1	0.06	0.13	0.20			
α	<i>0</i> °	-	12°			





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